

H-880G/H-880GP

High Tg, Middle Loss, Halogen Free

产品特点:

- Tg 170°C (DSC)
- Df 0.0100(1G)
- Td 390°C
- 阻燃等级 94UL-V0
- 厚度均匀性控制技术
- 适用无铅制程
- 优异的尺寸稳定性
- 低膨胀和优异的通孔可靠性
- IPC-4101E/127/128/130

应用领域:

多层板, LCD 背板, 服务器, 路由器, 基站及手机等。

Key Features:

- Tg 170°C (DSC)
- Df 0.0100(1G)
- Td 390°C
- Flammability Rating 94UL-V0
- Thickness uniformity control technology
- Lead free process compatible
- Excellent dimensional stability
- Low Z-axis CTE and excellent through hole reliability
- IPC-4101E/127/128/130

Applications:

Multilayer PCB, LCD Backpanel, Server, Office Router, Base station, Cellular Phone. etc

General properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature	2.4.24.4	DMA	°C	200
		2.4.25	DSC	°C	180
	X,Y 轴方向膨胀系数 X,Y-CTE	2.4.24.5	TMA	ppm/°C	12~14
	Z 轴方向膨胀系数 Z axis-CTE	2.4.24	TMA, Before TG	ppm/°C	40
			TMA, After TG	ppm/°C	200
			50~260°C	%	2.1
			T288	min	≧ 60
			T300	min	≧ 60
288°C 热冲击 Thermal stress	2.6.8	288°C, solder dip	S	Pass	

	热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	℃	390	
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	>10 ⁸	
	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	>10 ⁸	
	耐电弧 Arc Resistance	2.5.1	A	S	120	
	击穿电压 Dielectric Breakdown	2.5.6	A	KV	40	
	电气强度 Electric Strength(thickness<0.5mm)	2.5.6.2	A	KV/mm	40	
	相比耐漏电起痕指数 CTI	ASTM D3638	A	PLC(V)	3(175-249)	
	介电常数 Permittivity (RC54%)	2.5.5.9/2.5.5.13	1GHz	/	4.15/4.30	
			2.5.5.13	5GHz	/	4.26
				10GHz	/	4.23
	介电损耗 Loss Tangent (RC54%)	2.5.5.9/2.5.5.13	1GHz	/	0.0100/0.0110	
			2.5.5.13	5GHz	/	0.0120
10GHz				/	0.0130	
物理性能 Physical	弯曲强度 Flexural Strength	2.4.4	A	LW	MPa	500
				CW		400
	剥离强度 Peel Strength (1oz HTE)	2.4.8	288℃/10s		lb/inch	8.0
	阻燃等级 Flammability	UL94	UL94		/	V-0
	吸水率 Moisture Absorption	2.6.2.1	D-24/23		%	0.1

Specimen thickness: 1.50mm. Test Method is according to IPC TM-650 or GB.

The data above is only for reference, and the actual data will have deviation, according to varieties of test equipment and metho